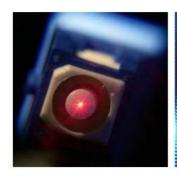


# **Product Catalog**









Fiber Optics Components and Services

2022



光貿易株式会社

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### Welcome

VI Systems GmbH (VIS) is a developer and manufacturer of optoelectronic components for optical communication, consumer and automotive applications. In the field of optical communications VIS offers optical components, such as vertical cavity surface-emitting lasers (VCSELs) and PIN photodiodes capable of up to 224 Gbps per channel and beyond. VIS VCSEL driver and PIN amplifier integrated circuits operate up to 56 Gbps with NRZ modulation. The latest generation of VCSEL and PIN photodiodes allow 400 Gbps PAM-4 energy efficient data transmission over one fiber with four channel short wave division multiplexing (SWDM) at 850 / 880 / 910 and 940 nm wavelength.



### **Table of Content**

Introduction		4
Fabless Con	npany Concept	5
Services for	optical component technology	
	Integrated Optical Solutions	6
	Wafer mapping services	7
	High frequency test and characterization	8
	Optical and mechanical measurements	9
	Modelling and simulation	10
Fiber couple	ed VCSEL transmitters (850/880/910 and 940 nm)	
•	up to 56 Gbps PAM-4 single channel module	11
	up to 112 Gbps PAM-4 single channel module	12
Fiber couple	ed VCSEL transmitters (1550nm)	
	up to 30 Gbps NRZ single channel module	13
Fiber couple	ed photodetectors and receiver modules	
	up to 56 Gbps NRZ single channel receiver	14
	up to 112 Gbps PAM-4 photodetector module	14
VCSEL drive	er ICs	
	up to 56 Gbps NRZ single channel driver	16
Transimpeda	ance amplifier ICs	
•	up to 56 Gbps NRZ single channel driver	17
VCSEL and I	PIN photodetector chips	
	850/880/910/940 nm VCSEL for up to 112 Gbps PAM-4	18
	840 - 1650 nm PIN PD for up to 112 Gbps PAM-4	19



### Company Introduction

VI Systems GmbH (VIS), is a fabless developer and manufacturer of ultrafast cost-effective optoelectronic devices for short reach optical communication interconnects and optical sensor applications. The company is located in center of Berlin - Charlottenburg, Germany in close proximity to leading research institutes and academic technical institutions.



Photo of the building at Hardenbergstr. 8 in Berlin. The company occupies two floors in the upper part of the building including a technical zone with electro-static-damage (ESD) protected work areas.

VI Systems GmbH offers optical subassemblies and fiber coupled modules for applications in optical data communications and optical sensing. In contrast to current optical- and electrical-based technologies, the optical solutions based on VIS components and systems will overcome the rising technological barriers created by the market driven continual increase in optical data transmission rates. With VIS proprietary solutions, telecom and computer equipment manufacturers will be able to meet the continuously growing performance requirements of the future.

Based on the Company's advanced proprietary technology, innovative design concepts, and technical expertise, VIS devices offer a unique combination of high speed, low power consumption, reliability, and low cost. VI Systems' uniqueness is based on its revolutionary concept of vertically-integrated modulator systems a new concept in ultrahigh-speed optical signal transmission and the integration into a low cost fiber optics components.

The company offers a range of optical components, integrated circuits and highly optimized packaging solutions as well as engineering services.



### Foundry based operation model

VI Systems designs and manufacturer optical components with the leading foundries in the world. Therefore the reliability of the process and the scalability is ensured from the very early stage of the development. Crucial steps in design and product verification are performed in-house. VI Systems operates a wafer inspection facility and a high speed test and device characterization laboratory in Berlin, Germany.

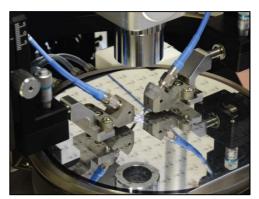


Photo: Wafer inspection systems at VI Systems

VI Systems concentrates on the design and qualification of ultrahigh-speed components for data transmission and high accuracy optical sensors. The manufacturing of optical components, integrated circuits and optical packaging is outsourced to foundries and electronics manufacturing service companies.

Our optical components and integrated products are sold to major manufacturing companies, who then use these components to produce high speed optical modules which are the basis of virtually all optical data transmitting systems.

VI Systems leads a trend in the fiber optic communications industry were manufacturers increasingly seeking to outsource production to specialized foundries in order to reduce overall costs and accelerate time to market.



### **Integrated Optical Solutions**

A novel concept of integrated ultrahigh-speed components is introduced by VI Systems. State-of-the art SiGe BICMOS integrated circuits are customized to match the performance of ultrahigh-speed optical VCSEL transmitter and PIN receiver components. Both key elements are assembled in a proprietary high frequency design to delivery outstanding performance over a wide temperature range.

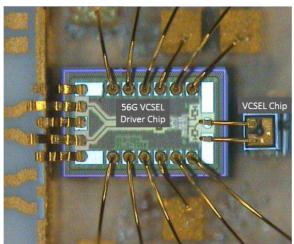


Photo: single channel 56G NRZ VCSEL driver with VCSEL chin

VI Systems offers a range of subcomponents for the use in short reach optical interconnects. The optical engines offer a unique combination of high speed, low power consumption, small footprint, high reliability and low cost.

VI Systems' unique selling point is based on a combination of its revolutionary concept of ultra-high frequency small footprint micro-assembly integration of advanced electro-optic components, development of advanced high speed ICs and development of modulation approaches.



#### Wafer mapping services

VI Systems new semi-automatic wafer prober station performs high-speed electrical and optical testing of wafers early in the manufacturing process. The system reduces manufacturing costs by eliminating out of specification wafers before they have been cut and packaged to improve yield.

We offer 100% wafer characterization of 2" to 8" wafer using an alignment camera with pattern recognition with automatic alignment to the chips. The test temperature to ranges from 25°C to 150°C. Measurement of L/I/V parameters, threshold current, slope efficiency, measurements of optical spectrum, photodiode sensitivity, reverse bias and dark current.

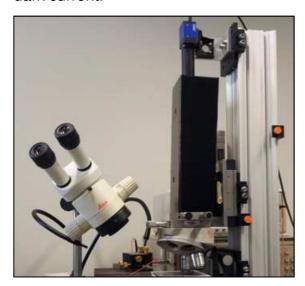


Photo: camera system for farfield studies

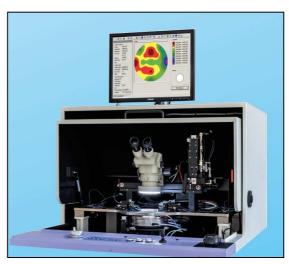


Photo: automatic wafer prober equipment

### Testing of optical emission characteristics

Our test station setup allows nearfield and farfield analysis of light emitting devices at temperatures of up to 150°C with a special interference-free infrared optics and camera

Nearfield measurements are performed to determine emitting diameter and mode emission characteristics as well as the measurement of mode field diameter and polarization characteristics.

Farfield measurements provide information on the angular distribution of power and the overall emission characteristics as well as the

maximum emission angle.



### High frequency test services

Our high frequency test laboratory allows a detailed analysis of the electro-optical performance of chip level devices. For general bandwidth measurement a sine wave frequency generator for up to 38 GHz can be combined with a 70 GHz sampling oscilloscope. For optical test a 32 GHz detector for 700nm to 1600nm is available.

Specific optical data modulation characteristics and eye-diagram measurements of up to 128 Gbit/s can be performed. Our bit pattern generator generates a range of standard pseudo random bit sequences such as PRBS7 and PRBS31. For high speed test of short reach application at 850nm wavelength a range photodetector and photoreceiver modules with for up to 112 Gbit/s are available.

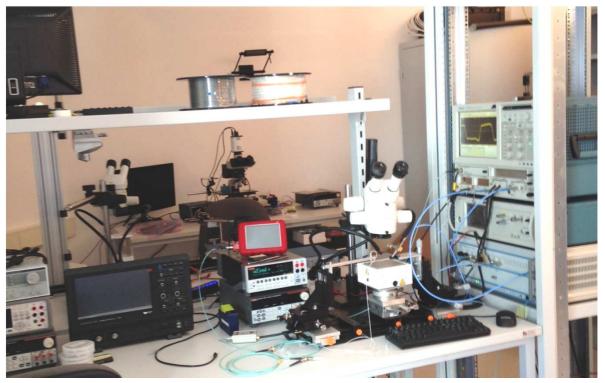


Photo: high frequency test laboratory for data transmission experiments



### Optical and Mechanical Inspection

We offer a range of inspection tools to determine the the properties of optical components. Our laboratory is equipped with conventional optical microscopes with a magnification of up to 1000 times.

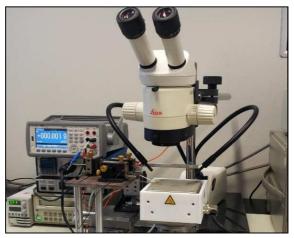


Photo: stereo microscope with temperature chuck

More complex studies using focused ion beam (FIB), scanning electron microscopy (SEM) and transmission electron microscopy (TEM) are performed with external test partners

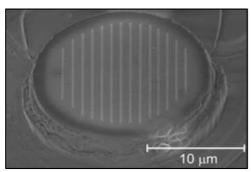


Image: structure analysis with TEM

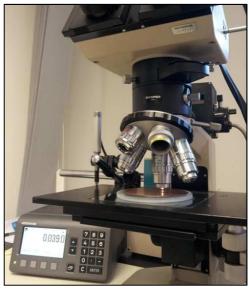


Photo: high resolution optical microscope

With our thickness analysis technology we can determine horizontal dimensions with resolution of 0.1 µm and vertical dimensions with a resolution of 0.5 µm.

#### Testing of VCSEL, LED, PD, APD

Our microprober station allows on-wafer characterization test in a wide temperature rang. For static test we can measure electrical charateristics such as forward and reverse voltage or current and differential resistance. Optical test characteristics include paramters such As power, spectrum, sensitivity, efficiency, threashold current, slope efficiency and amplification



#### Thermal analysis

Simulation tools for the thermal modeling of semiconductor packages have now become routine in most design processes. From early spreadsheet-type tools that were in vogue a couple of decades ago, many designers now use sophisticated FEA (Finite Element Analysis) or CFD (Computational Fluid Dynamics) tools, and interface their mechanical CAD data directly into their analysis.

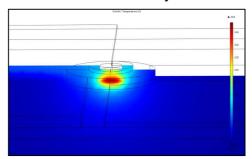


Image: Thermal distribution in a VCSEL

### Modelling and simulation

VCSELs are key components for optical interconnects and are widely applied in high-performance computers and data centers. Single transverse-mode VCSELs are used in sensing, illumination, and display applications. The image below shows a cross section of the simulated electric field of the fundamental and first excited optical modes of an oxide-confined aluminum gallium arsenide-based leaky VCSEL.

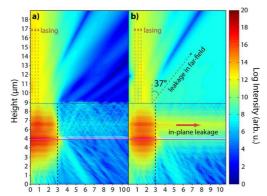


Image: Radial distribution of the simulated electric field of oxide-confined leaky vertical-cavity surface-emitting laser (VCSEL) optical modes. (a) Fundamental optical mode. (b) First excited mode.

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### VCSEL transmitter modules

### V25-850M Transmitter Module (up to 28 Gbps NRZ)



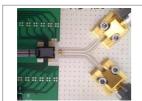
Parameter	Typical
Emission Wavelength	850 nm
Data rate (NRZ)	28 Gbps
Fiber Type	50/125 μm

V50-850M Transmitter Module (up to 56 Gbps PAM-4)



Parameter	Typical
Emission Wavelength	850 nm
Data rate (PAM-4)	56 Gbps
Fiber Type	50/125 μm

T56-850 Transmitter subassembly for up to 56 Gbps



Parameter	Typical
Emitting Wavelength	850 nm
Data rate (NRZ)	56 Gbps
Fiber Type	50/125 μm

VM100-850M Transmitter Module (up to 112 Gbps PAM-4)



Parameter	Typical
Emission Wavelength	850 nm
Data rate (PAM-4)	112 Gbps
Fiber Type	50/125 μm

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### VCSEL transmitter module

### VM100-880M Transmitter Module for up to 112 Gbps PAM-4



Parameter	Typical
Emission Wavelength	880 nm
Data rate (PAM-4)	112 Gbps
Fiber Type	50/125 μm

VM100-910M Transmitter Module for up to 112 Gbps PAM-4



Parameter	Typical
Emission Wavelength	910 nm
Data rate (PAM-4)	112 Gbps
Fiber Type	50/125 μm

VM100-940M Transmitter Module for up to 112 Gbps PAM-4



Parameter	Typical
Emission Wavelength	940 nm
Data rate (PAM-4)	112 Gbps
Fiber Type	50/125 μm



## VCSEL transmitter module (long wavelength)

### V30-1550M Transmitter Module (up to 30 Gbps NRZ)

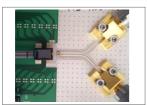


Parameter	Typical
Emission Wavelength	1550 nm
Data rate (NRZ)	30 Gbps
Fiber Type	9/125 μm



## Optical receiver and photodetetor modules

R50-850 Receiver subassembly for up to 56 Gbps



Parameter	Typical
Input wavelength	700 - 870 nm
Data rate (NRZ)	56 Gbps
Fiber Type	50/125 μm

D30-850M Photodetector Module for up to 112 Gbps



Parameter	Typical
Input wavelength	840 - 1650 nm
Data rate (PAM-4)	112 Gbps
Fiber Type	50/125 μm



**Typical** 

### **VCSEL Driver ICs**

#### A56-230C High Speed VCSEL driver



Data rate up to 56 Gbps
Supply voltage 3.3 V
Power dissipation 230 mW

**Parameter** 

A56-105C High Speed VCSEL driver



Parameter	Typical
Data rate	up to 56 Gbps
Supply voltage	3.3 V
Power dissipation	105 mW

#### A56-xxxC\_DRV\_TB VCSEL driver evaluation board

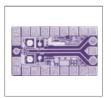


Parameter	Typical
Data rate (NRZ)	up to 100 Gbps
Supply voltage	3.3 V
Power dissipation	230 mW

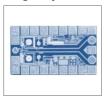


## Transimpedance Amplifier (TIA)

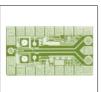
### T56-250C\_V1.1 High Speed TIA



### T56-250C\_V1.2 High Speed TIA



### T56-150C \_2.0 High Speed TIA



Parameter	Typical
Supply voltage	3.3 V
Data rate (NRZ)	56 Gbps
Power dissipation	250 mW

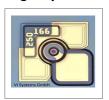
Parameter	Typical
Supply voltage	3.3 V
Data rate (NRZ)	56 Gbps
Power dissipation	250 mW

Parameter	Typical
Supply voltage	3.3 V
Data rate (NRZ)	56 Gbps
Power dissipation	150 mW



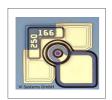
## VCSEL Chips (850nm and SWDM)

### V25-850C High-Speed VCSEL Chip



Parameter	Typical
Emission Wavelength	850 nm
Peak Output Power	4 mW
Data rate (NRZ)	28 Gbps

V50-850C High Speed VCSEL Chip



Parameter	Typical
Emission Wavelength	850 nm
Peak Output Power	4 mW
Data rate (NRZ)	56 Gbps

VM100-xxxC High Speed VCSEL Chip



Parameter	Typical
Emission Wavelength	850 / 880 / 910 / 940 nm
Peak Output Power	4 mW
Data rate (PAM-4)	112 Gbps

V4M100-xxxC High Speed VCSEL mini array Chip



Parameter	Typical
Emission Wavelength	850 / 880 / 910 / 940 nm
Peak Output Power	3 mW
Data rate (PAM-4)	112 Gbps

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## Broad Range Photodetector PIN Diode

### Dxx-BROAD-Cxx High Speed Photodetector



Parameter	Typical
Operating Wavelength	800-1650 nm
Bandwidth	~ 40 GHz
Available chip type	1-ch / 4-ch



### **VI Systems GmbH**

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